

What is claimed is:

1. A method of detecting a polishing end point in a chemical
5 mechanical polishing process, comprising the steps of:

using a sensor detecting variation in the concentration of a material
within an initial polishing layer or a material within a polishing stop layer,
which are contained in polishing wastewater drained during a polishing
process;

10 using an EDP system to database information detected by the sensor;

feeding back the result to a polisher in real time, wherein if a result that
there is no change in the concentration of the material within the initial
polishing layer is obtained, the polishing process continuously proceeds with
an initial polishing process condition;

15 if a result that variation in the concentration of the material within the
initial polishing layer is reduced and variation in the concentration of the
material within the polishing stop layer is increased, is obtained, performing
the polishing process by lowering a polishing pressure; and

if a result that variation in the concentration of the material within the
20 initial polishing layer is not reduced but kept constant and variation in the
concentration of the material within the polishing stop layer is not increased
but kept constant, is obtained, using the EPD system to send a polishing
process stop signal to the polisher, thus stopping the polishing process.